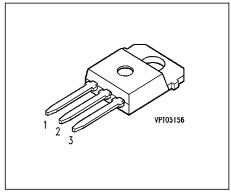


SIPMOS ® Power Transistor

BUZ 341

- N channel
- Enhancement mode
- Avalanche-rated



Pin 1	Pin 2	Pin 3
G	D	S

Туре	V _{DS}	I _D	R _{DS(on)}	Package	Ordering Code
BUZ 341	200 V	33 A	0.07 Ω	TO-218 AA	C67078-S3128-A2

Maximum Ratings

Parameter	Symbol	Values	Unit
Continuous drain current	I _D		Α
$T_{\rm C}$ = 28 °C		33	
Pulsed drain current	I _{Dpuls}		
$T_{\rm C}$ = 25 °C		132	
Avalanche current, limited by T_{jmax}	I _{AR}	33	
Avalanche energy, periodic limited by T_{jmax}	E _{AR}	16	mJ
Avalanche energy, single pulse	E _{AS}		
$I_{\rm D} = 33 \; {\rm A}, \; V_{\rm DD} = 50 \; {\rm V}, \; R_{\rm GS} = 25 \; \Omega$			
$L = 1.09 \text{ mH}, T_j = 25 \text{ °C}$		790	
Gate source voltage	V_{GS}	± 20	V
Power dissipation	P _{tot}		W
$T_{\rm C}$ = 25 °C		170	
Operating temperature	$T_{\rm j}$	-55 + 150	°C
Storage temperature	$T_{ m stg}$	-55 + 150	
Thermal resistance, chip case	R _{thJC}	≤ 0.74	K/W
Thermal resistance, chip to ambient	R_{thJA}	75	
DIN humidity category, DIN 40 040		E	
IEC climatic category, DIN IEC 68-1		55 / 150 / 56	



Electrical Characteristics, at $T_j = 25$ °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static Characteristics					
Drain- source breakdown voltage	V _{(BR)DSS}				V
$V_{\rm GS}$ = 0 V, $I_{\rm D}$ = 0.25 mA, $T_{\rm j}$ = 25 °C		200	-	-	
Gate threshold voltage	V _{GS(th)}				
$V_{\text{GS}} = V_{\text{DS}}$, $I_{\text{D}} = 1 \text{ mA}$		2.1	3	4	
Zero gate voltage drain current	IDSS				μΑ
$V_{\mathrm{DS}} = 200 \; \mathrm{V}, \; V_{\mathrm{GS}} = 0 \; \mathrm{V}, \; T_{\mathrm{j}} = 25 \; \mathrm{^{\circ}C}$		-	0.1	1	
$V_{\rm DS} = 200 \text{ V}, \ V_{\rm GS} = 0 \text{ V}, \ T_{\rm j} = 125 \ ^{\circ}\text{C}$		-	10	100	
Gate-source leakage current	I _{GSS}				nA
$V_{\text{GS}} = 20 \text{ V}, \ V_{\text{DS}} = 0 \text{ V}$		-	10	100	
Drain-Source on-resistance	R _{DS(on)}				Ω
$V_{GS} = 10 \text{ V}, I_D = 21 \text{ A}$		-	0.06	0.07	



Electrical Characteristics, at $T_j = 25$ °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Dynamic Characteristics					
Transconductance	g _{fs}				S
$V_{DS} \ge 2 * I_D * R_{DS(on)max}, I_D = 21 A$		15	23	-	
Input capacitance	C_{iss}				pF
$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		-	2600	3900	
Output capacitance	C_{oss}				
$V_{GS} = 0 \text{ V}, \ V_{DS} = 25 \text{ V}, \ f = 1 \text{ MHz}$		-	500	750	
Reverse transfer capacitance	C_{rss}				
$V_{GS} = 0 \text{ V}, \ V_{DS} = 25 \text{ V}, \ f = 1 \text{ MHz}$		-	230	350	
Turn-on delay time	$t_{d(on)}$				ns
$V_{\rm DD}$ = 30 V, $V_{\rm GS}$ = 10 V, $I_{\rm D}$ = 3 A					
$R_{\rm GS}$ = 50 Ω		-	40	60	
Rise time	t _r				
$V_{\rm DD}$ = 30 V, $V_{\rm GS}$ = 10 V, $I_{\rm D}$ = 3 A					
$R_{\rm GS}$ = 50 Ω		-	110	170	
Turn-off delay time	$t_{d(off)}$				
$V_{\rm DD} = 30 \; {\rm V}, \; V_{\rm GS} = 10 \; {\rm V}, \; I_{\rm D} = 3 \; {\rm A}$					
$R_{\rm GS}$ = 50 Ω		-	450	680	
Fall time	t_{f}				
$V_{\rm DD}$ = 30 V, $V_{\rm GS}$ = 10 V, $I_{\rm D}$ = 3 A					
$R_{\rm GS}$ = 50 Ω		-	160	240	



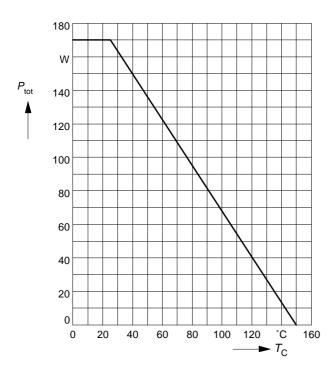
Electrical Characteristics, at $T_j = 25$ °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Reverse Diode					
Inverse diode continuous forward current	I _S				А
$T_{\rm C}$ = 25 °C		-	-	33	
Inverse diode direct current,pulsed	/ _{SM}				
$T_{\rm C}$ = 25 °C		-	-	132	
Inverse diode forward voltage	V_{SD}				V
$V_{GS} = 0 \text{ V}, I_{F} = 66 \text{ A}$		-	1.3	1.6	
Reverse recovery time	t _{rr}				ns
$V_{\rm R} = 100 \ {\rm V}, \ I_{\rm F} = I_{\rm S}, \ {\rm d}i_{\rm F}/{\rm d}t = 100 \ {\rm A/\mu s}$		-	230	-	
Reverse recovery charge	Q_{rr}				μC
$V_{\rm R}$ = 100 V, $I_{\rm F} = I_{\rm S}$, $di_{\rm F}/dt$ = 100 A/µs		-	1.8	-	



Power dissipation

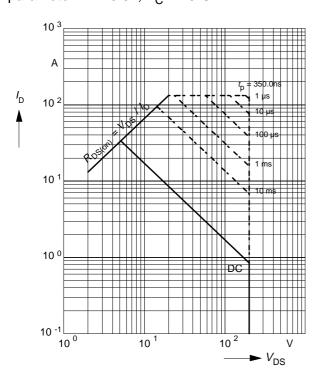
$$P_{\mathsf{tot}} = f(T_{\mathsf{C}})$$



Safe operating area

 $I_{\mathsf{D}} = f(V_{\mathsf{DS}})$

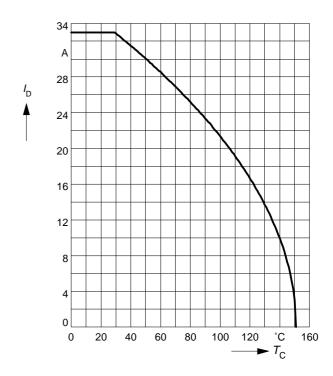
parameter: D = 0.01, $T_C = 25$ °C



Drain current

 $I_{\mathsf{D}} = f(T_{\mathsf{C}})$

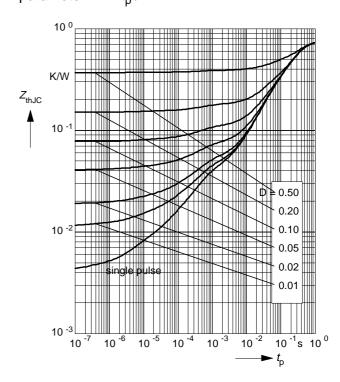
parameter: V_{GS} ≥ 10 V



Transient thermal impedance

 $Z_{\text{th JC}} = f(t_{\text{p}})$

parameter: $D = t_p / T$

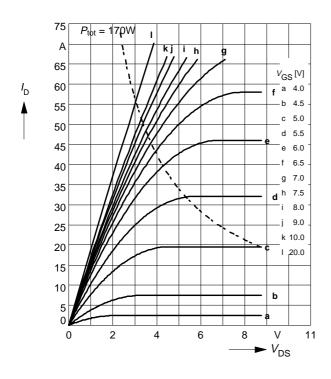




Typ. output characteristics

 $I_{\mathsf{D}} = f(V_{\mathsf{DS}})$

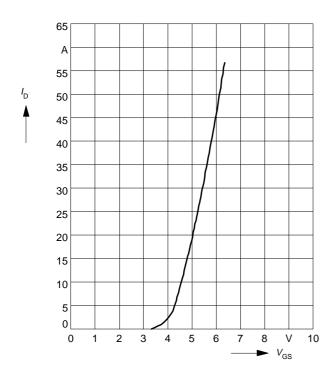
parameter: $t_p = 80 \mu s$



Typ. transfer characteristics $I_{D} = f(V_{GS})$

parameter: $t_p = 80 \mu s$

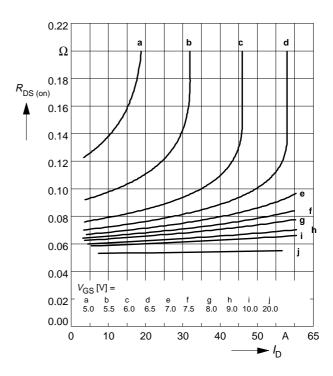
 $V_{\text{DS}} \ge 2 \times I_{\text{D}} \times R_{\text{DS(on)max}}$



Typ. drain-source on-resistance

 $R_{\mathrm{DS}\;(\mathrm{on})} = f(I_{\mathrm{D}})$

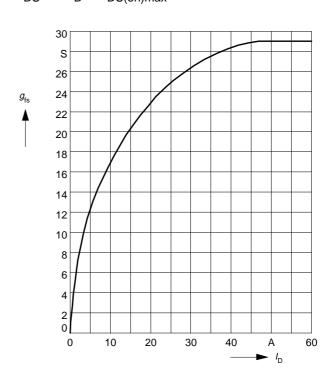
parameter: V_{GS}



Typ. forward transconductance $g_{fs} = f(I_D)$

parameter: $t_p = 80 \mu s$,

 $V_{DS} \ge 2 \times I_D \times R_{DS(on)max}$

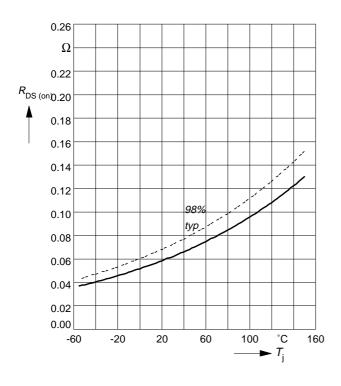




Drain-source on-resistance

 $R_{\text{DS (on)}} = f(T_{j})$

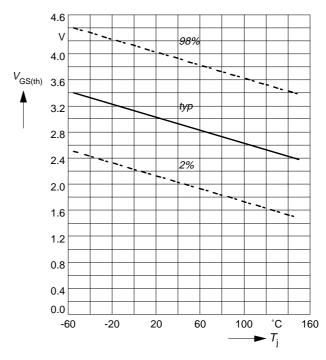
parameter: $I_D = 21 \text{ A}$, $V_{GS} = 10 \text{ V}$



Gate threshold voltage

 $V_{\text{GS (th)}} = f(T_{j})$

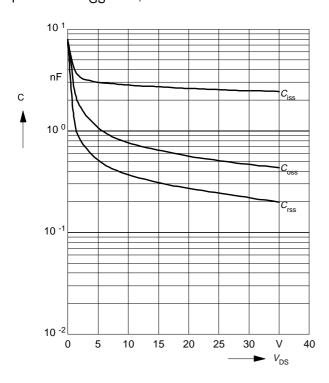
parameter: $V_{GS} = V_{DS}$, $I_{D} = 1 \text{ mA}$



Typ. capacitances

 $C = f(V_{DS})$

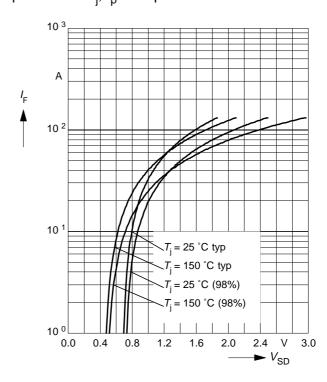
parameter: $V_{GS} = 0V$, f = 1MHz



Forward characteristics of reverse diode

 $I_{\mathsf{F}} = f(V_{\mathsf{SD}})$

parameter: T_i , $t_p = 80 \mu s$





Avalanche energy $E_{\rm AS} = f(T_{\rm j})$ parameter: $I_{\rm D} = 33$ A, $V_{\rm DD} = 50$ V $R_{\rm GS} = 25~\Omega,~L = 1.09~{\rm mH}$

